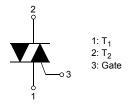


### FKPF5N80

### **Application Explanation**

- Switching mode power supply, light dimmer, electric flasher unit
- TV sets, stereo, refrigerator, washing machine, bread maker
- Electric blanket, solenoid driver, small motor control
- · Photo copier, electric tool





# **Bi-Directional Triode Thyristor Planar Silicon**

### Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

| Symbol           | Parameter                                 | Rating | Units |
|------------------|---|--------|-------|
| V <sub>DRM</sub> | Repetitive Peak Off-State Voltage (Note1) | 800    | V     |

| Symbol               | Parameter                                 | Conditions  |      | Rating     | Units            |
|----------------------|---|---|------|------------|------------------|
| I <sub>T (RMS)</sub> | RMS On-State Current                      | Commercial frequency, sine full wave 360° conduction, T <sub>C</sub> =104°C |      | 5          | Α                |
| I <sub>TSM</sub>     | Surge On-State Current                    | Sinewave 1 full cycle, peak value,  | 50Hz | 50         | Α                |
|                      |   | non-repetitive 60   |      | 55         | Α                |
| I <sup>2</sup> t     | I <sup>2</sup> t for Fusing               | Value corresponding to 1 cycle of halfwave, surge on-state current, tp=10ms |      | 12.5       | A <sup>2</sup> s |
| di/dt                | Critical Rate of Rise of On-State Current | I <sub>G</sub> = 2x I <sub>GT</sub> , tr ≤ 100ns                            |      | 50         | A/μs             |
| $P_{GM}$             | Peak Gate Power Dissipation               |   |      | 5          | W                |
| P <sub>G (AV)</sub>  | Average Gate Power Dissipation            |   |      | 0.5        | W                |
| $V_{GM}$             | Peak Gate Voltage                         |   |      | 10         | V                |
| I <sub>GM</sub>      | Peak Gate Current                         |   |      | 2          | Α                |
| T <sub>J</sub>       | Junction Temperature                      |   |      | - 40 ~ 125 | °C               |
| T <sub>STG</sub>     | Storage Temperature                       |   |      | - 40 ~ 125 | °C               |
| V <sub>iso</sub>     | Isolation Voltage                         | Ta=25°C, AC 1 minute, T <sub>1</sub> T <sub>2</sub> G terminal to case      |      | 1500       | V                |

### **Thermal Characteristic**

| Symbol        | Parameter          | Test Condition            | Min. | Тур. | Max. | Units |
|---------------|--------------------|---------------------------|------|------|------|-------|
| $R_{th(J-C)}$ | Thermal Resistance | Junction to case (Note 4) | ı    | ı    | 3.9  | °C/W  |

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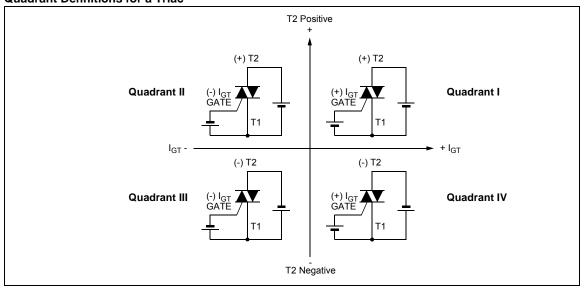
# $\textbf{Electrical Characteristics} \ \, \textbf{T}_{\text{C}} = 25^{\circ} \text{C unless otherwise noted}$

| Symbol               | Parameter  |        | Test Condition   |                 | Min. | Тур. | Max. | Units |
|----------------------|--|--------|--|-----------------|------|------|------|-------|
| I <sub>DRM</sub>     | Repetieive Peak Off-State Current V <sub>DRM</sub> applied         |        | -  | -               | 20   | μΑ   |      |       |
| V <sub>TM</sub>      | On-State Voltage   |        | T <sub>C</sub> =25°C, I <sub>TM</sub> =7.5A<br>Instantaneous measurement |                 | -    | -    | 1.5  | V     |
|                      | 41.4.0   | I      | V <sub>D</sub> =12V, R <sub>L</sub> =20Ω                                 | T2(+), Gate (+) | -    | -    | 1.5  | V     |
| $V_{GT}$             | Gate Trigger Voltage (Note 2)                                      | II     |  | T2(+), Gate (-) | -    | -    | 1.5  | V     |
|                      |  | III    |  | T2(-), Gate (-) | -    | -    | 1.5  | V     |
|                      | 41.4.0   | I      | V <sub>D</sub> =12V, R <sub>L</sub> =20Ω                                 | T2(+), Gate (+) | -    | -    | 20   | mA    |
| $I_{GT}$             | Gate Trigger Current (Note 2)                                      | II     |  | T2(+), Gate (-) | -    | -    | 20   | mA    |
|                      |  | III    |  | T2(-), Gate (-) | -    | -    | 20   | mA    |
| $V_{GD}$             | Gate Non-Trigger Voltage   |        | T <sub>J</sub> =125°C, V <sub>D</sub> =1/2V <sub>DRM</sub>               |                 | 0.2  | -    | -    | V     |
| I <sub>H</sub>       | Holding Current  |        | V <sub>D</sub> = 12V, I <sub>TM</sub> = 1A                               |                 | -    | -    | 30   | mA    |
| IL                   | Latching Current   | I, III | $V_D = 12V, I_G = 1.2I_{GT}$   |                 | -    | -    | 30   | mA    |
|                      |  | II     |  |                 | -    | -    | 50   | mA    |
| dv/dt                | Critical Rate of Rise of<br>Off-State Voltag                       |        | V <sub>DRM</sub> = Rated, T <sub>j</sub> = 125°C<br>Exponential Rise     | ·,              | -    | 300  | -    | V/μs  |
| (dv/dt) <sub>C</sub> | Critical-Rate of Rise of Off-State<br>Commutating Voltage (Note 3) |        |  |                 | 10   | -    | -    | V/µs  |

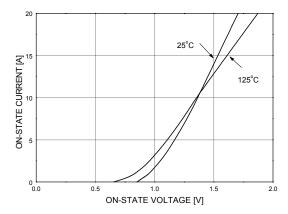
- Notes:
  1. Gate Open
  2. Measurement using the gate trigger characteristics measurement circuit
  3. The critical-rate of rise of the off-state commutating voltage is shown in the table below
  4. The contact thermal resistance R<sub>TH(c-f)</sub> in case of greasing is 0.5 °C/W

| Test Condition   | Commutating voltage and current waveforms (inductive load)  |
|--|---|
| 1. Junction Temperature T <sub>J</sub> =125°C                                    | Supply Voltage Time   |
| 2. Rate of decay of on-state commutating current (di/dt) <sub>o</sub> = -3 0A/ms | Main Current (di/dt) <sub>C</sub> Time  |
| 3. Peak off-state voltage V <sub>D</sub> = 400V                                  | Main Voltage Time   |
| _  | <ol> <li>Junction Temperature         T<sub>J</sub>=125°C</li> <li>Rate of decay of on-state         commutating current         (di/dt)<sub>C</sub> = - 3.0A/ms</li> <li>Peak off-state voltage</li> </ol> |

### **Quadrant Definitions for a Triac**



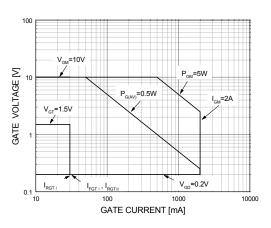
# **Typical Curves**



NUMBER OF CYCLES AT 50Hz AND 60Hz

Figure 1. Maximum On-state Characteristics

Figure 2. Rated Surge On-state Current



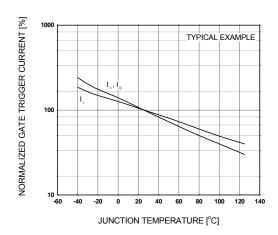
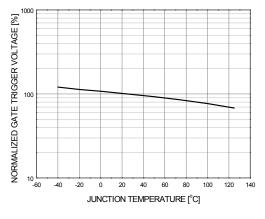


Figure 3. Gate Characteristics

Figure 4. Gate Trigger Current vs Tj



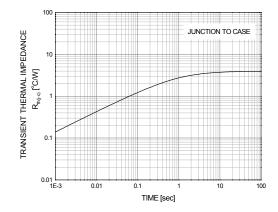


Figure 5. Gate Trigger Voltage vs Tj

Figure 6. Transient Thermal Impedance

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# Typical Curves (Continues)

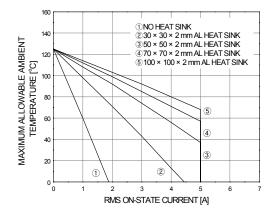


Figure 7. Allowable Ambient Temperature vs Rms On-state Current

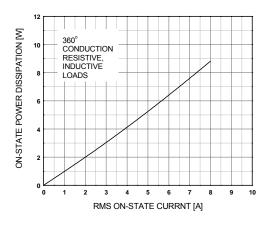


Figure 9. Maximum On-state Power Dissipation

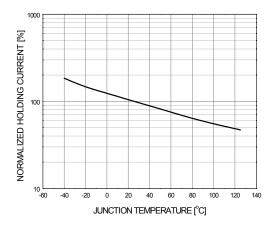


Figure 11. Holding Current vs
Junction Temperature

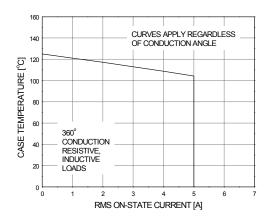


Figure 8. Allowable Case Temperature vs Rms On-state Current

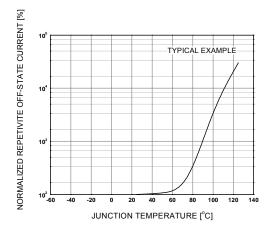


Figure 10. Repetitive Peak Off-state Current vs Junction Temperature

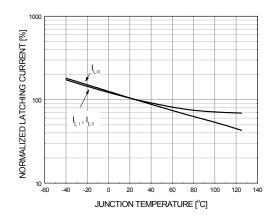


Figure 12. Laching Current vs
Junction Temperature

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# Typical Curves (Continues)

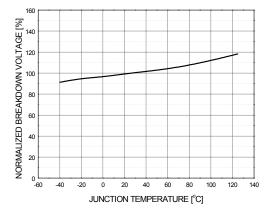


Figure 13. Breakover Voltage vs. Junction Temperature

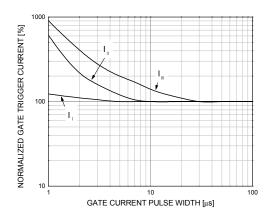


Figure 14. Gate Trigger Current vs.
Gate Current Pulse Width

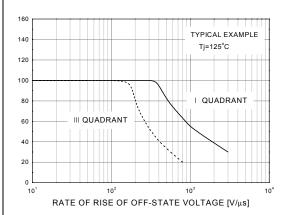


Figure 15. Breakover Voltage vs. Rate of Rise of Off-State Voltage

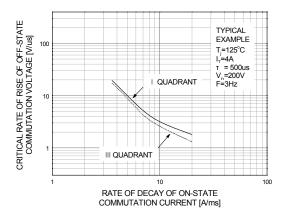
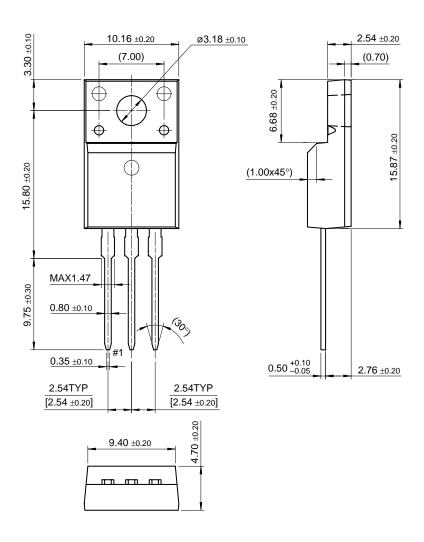


Figure 16. Commutation Characteristics

# **Package Dimension**

# TO-220F



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| Across the boar                   | d. Around the world.™          | OCXPro™            | RapidConnect™       | UHC™                   |
| The Power Fran                    | chise <sup>®</sup>             | OPTOLOGIC®         | SILENT SWITCHER®    | UltraFET <sup>®</sup>  |
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